GLPOLY

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点胶式液态导热垫片 XK-S15LV®

Thermal Conductivity Silicone Gel XK-S15LV

特性：

1:1混合（無副產品）

1:1mix(no cure by-product)

低應力應用

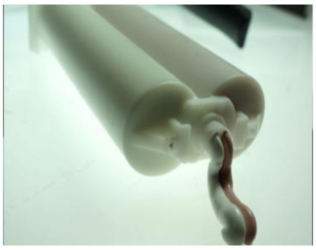
low stress applications

操作方便

Easy to Use

加熱加速反應

Hear Fast Cure



應用：

汽車電子

Automotive electronics

通訊設

Telecommunications

電腦及周邊產品

Computer & peripherals

導熱，減震

Thermally conductive vibration dampening

熱源與散熱器間應用

Between any heat-generating semiconductor and a heat sink

	XK-S15LV	**METHOD**	**UNIT**
Color / Part A	Gray	Visual	
Color / Part B	White	Visual	
Features	Soft GEL	-	-
Density	1.9	ASTM D792	g/cm3
Before Cured Property			
A:B	1:1	-	-
Mixed Viscosity	230,000	ASTM D2196	cps
Shelf Life @ 25℃	6 month		
After Cured Property			
Color	Gray	Visual	-
Cure Schedule 1	12hr/25℃		
Cure Schedule 2	10min/80℃		
Cure Schedule 3	5min/100℃		
Working time	60 Min/25℃		
Hardness	Shore 00 = 30	ASTM D2240	
	AskerC = 8	JIS K7312	
Tensile Strength.	0.7	ASTM D412	Mpa
Elongation	225	ASTM D412	%
Continuous Use Temp	-60~180		℃
Electrical Property			
Dielectric strength	>10	ASTM D149	KV/mm
Volume resistivity	$>10^{13}$	ASTM D257	Ohm-cm
Dielectric Constant	5.0	ASTM D150	(1Khz)
Flame Rating	V-0	UL94	
Thermal Property			
Thermal Conductivity	1.5	ASTM D5470	W/m*K
Heat Capacity	1.0	ASTM E1269	J/g-K

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